



Form 1449 (Modified)

**Information Disclosure
Statement By Applicant**
(Use Several Sheets if Necessary)

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Applicant:
KLA-Tencor
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Application No.:
10/691,940

Group 2881
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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>AB</i>	A	5,877,498	03/02/99	Sugimoto et al.			07/15/97
<i>AB</i>	B	5,900,645	05/04/99	Yoshinki Yamada			11/21/97
<i>AB</i>	C	6,351,516	02/26/02	Mazor et al.			12/14/99
	D						
	E						
	F						
	G						
	H						
	I						

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
<i>AB</i>	O	Amekura, Hiroshi et al., <i>X-Ray Emission Induced by 60 keV High-Flux Copper Negative-Ion Implantation</i> , February 2001, Japan Society of Applied Physics.
<i>AB</i>	P	Shaw, Judy B. et al., <i>Voids, Pits, and Copper</i> , Winter 2002, Yield Management Solutions: Cu/low Special Focus.
<i>AB</i>	Q	Testoni, A.L., <i>CuVA: Analyzing Voids in Cu Interconnects</i> , June 20, 2002, KLA-Tencor Progress Report.
Examiner	<i>Milata Bella</i>	
	Date Considered <i>February 15, 2005</i>	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.